L Number	Hits	Search Text	DB	Time stamp
56	16548	bump near2 (electrode conduct$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:28
57	4643787	via hole plug stud	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:29
58	7781	(bump near2 (electrode conduct$3)) and (via hole plug stud)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:29
59	531712	(dielectric insulat$3) near (layer film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:30
60	3433	((bump near2 (electrode conduct$3)) and (via hole plug stud)) and ((dielectric insulat$3) near (layer film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:31
63	677	(((bump near2 (electrode conduct$3)) and (via hole plug stud)) and ((dielectric insulat$3) near (layer film))) and gate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/28 15:32

C:\APPS\east\workspaces\10076154-interlayer.wsp